

**REMARKS**

Applicant respectfully requests entering of the foregoing specification amendment prior to examination of the present application.

Applicant believes that the present application is now in condition for allowance. Favorable reconsideration of the application as amended is respectfully requested.

The Examiner is invited to contact the undersigned by telephone if it is felt that a telephone interview would advance the prosecution of the present application.

Respectfully submitted,

Date April 16, 2002

By 

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Customer Number: 26371



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**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

[0043] As with seed layers described with reference to FIGURES 1-3, seed layer 440 includes elements implanted in a [UELII] ULEII process. Examples of elements that can be implanted include Zn, Sn, Cr, Ca, Ag, or In. Such implanted elements can be reactive with barrier layer 430, thereby reducing resistance and improving electromigration effects. A [UELII] ULEII process has the advantage of avoiding the manufacture of copper alloy targets, such as those necessary in a plasma vapor deposition (PVD) tooled process.